Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-4. (Canceled)

5. (Currently Amended) A method of manufacturing an electronic device, the method comprising:

preparing a chip component and a substrate, the chip component having a base material, the chip component having a first surface on which a pad is formed and a passivation film is formed to avoid at least a part of the pad, the chip component having a second surface being opposite to the first surface, the substrate having ~~a~~ an interconnect pattern;

providing an insulating adhesive on the substrate;

mounting the chip component on the insulating adhesive in such a manner that the second surface faces the insulating adhesive with applying a compressive force between the substrate and the chip component so that the insulating adhesive has a first part and a second part, the first part being interposed between the chip component and the substrate, the second part being disposed adjacent to the chip component, the second part having a convex surface that draws a curve on a view from which a cross section perpendicular to the first surface of the chip component is taken, the convex surface ascending from the first surface to have a top surface and descending from the top surface in an outward direction;

forming a metal layer that includes a plurality of layers including a diffusion prevention layer in contact with the pad and an uppermost layer being less oxidizable than the pad, the diffusion prevention layer preventing any diffusion of material formed thereabove into the base material of the chip component; and

forming an interconnect in such a manner as to extend from above the uppermost layer of the metal layer to above the interconnect pattern, as to have a first section disposed on the passivation film and a second section disposed over the insulating section, and as to cover all the lateral surfaces of the metal layer.

6. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the interconnect is formed of a dispersant including electrically conductive particles.

7. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the step of forming the interconnect includes ejecting the dispersant including the electrically conductive particles over the metal layer, the insulating section and the interconnect pattern.

8. (Original) The method of manufacturing an electronic device as defined by claim 5,

wherein the insulating section is formed of a resin.

9. (Original) The method of manufacturing an electronic device as defined by claim 6,

wherein the insulating section is formed of a resin.

10. (Original) The method of manufacturing an electronic device as defined by claim 7,

wherein the insulating section is formed of a resin.

11-27. (Canceled)